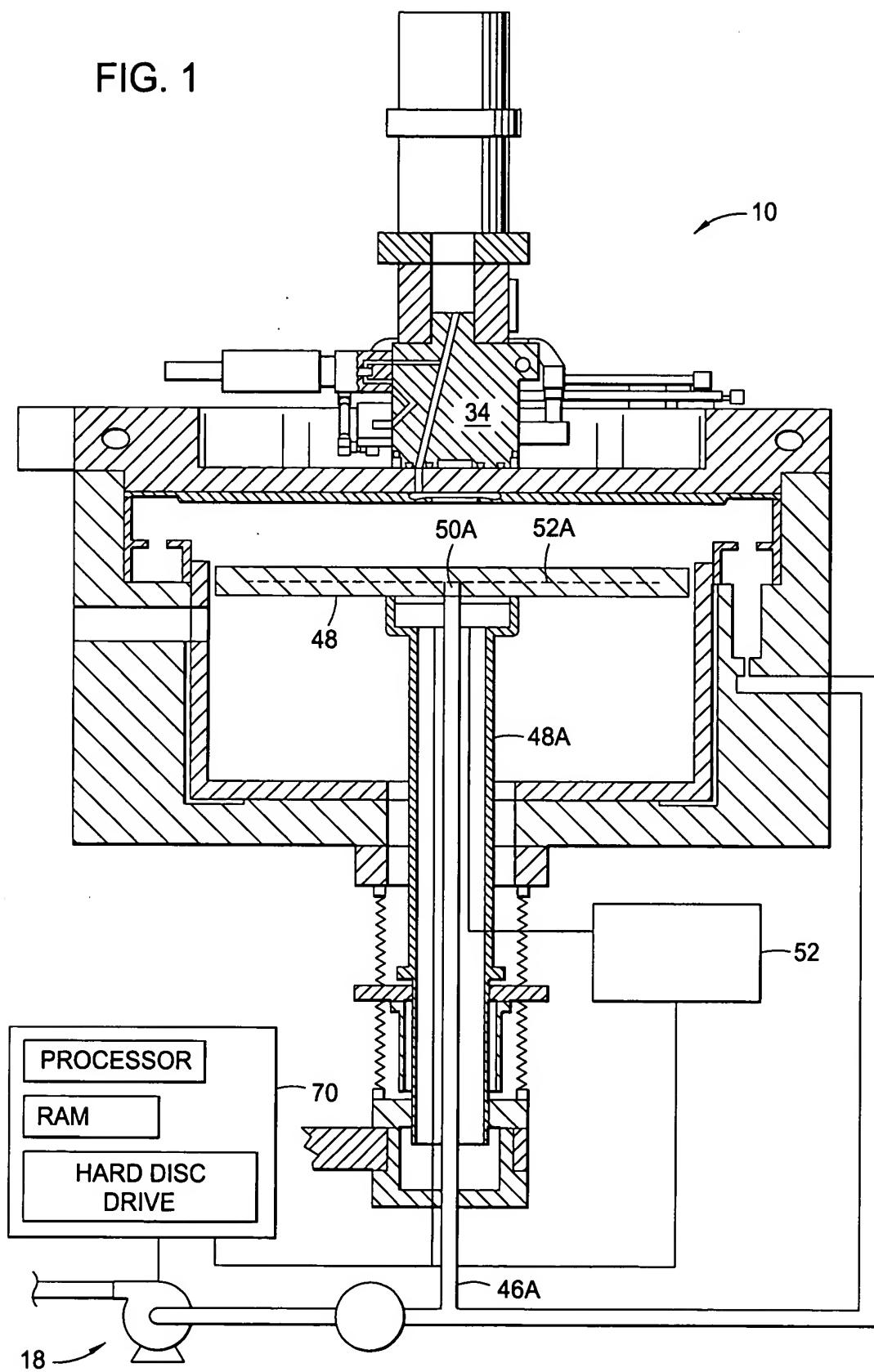


1/5

FIG. 1



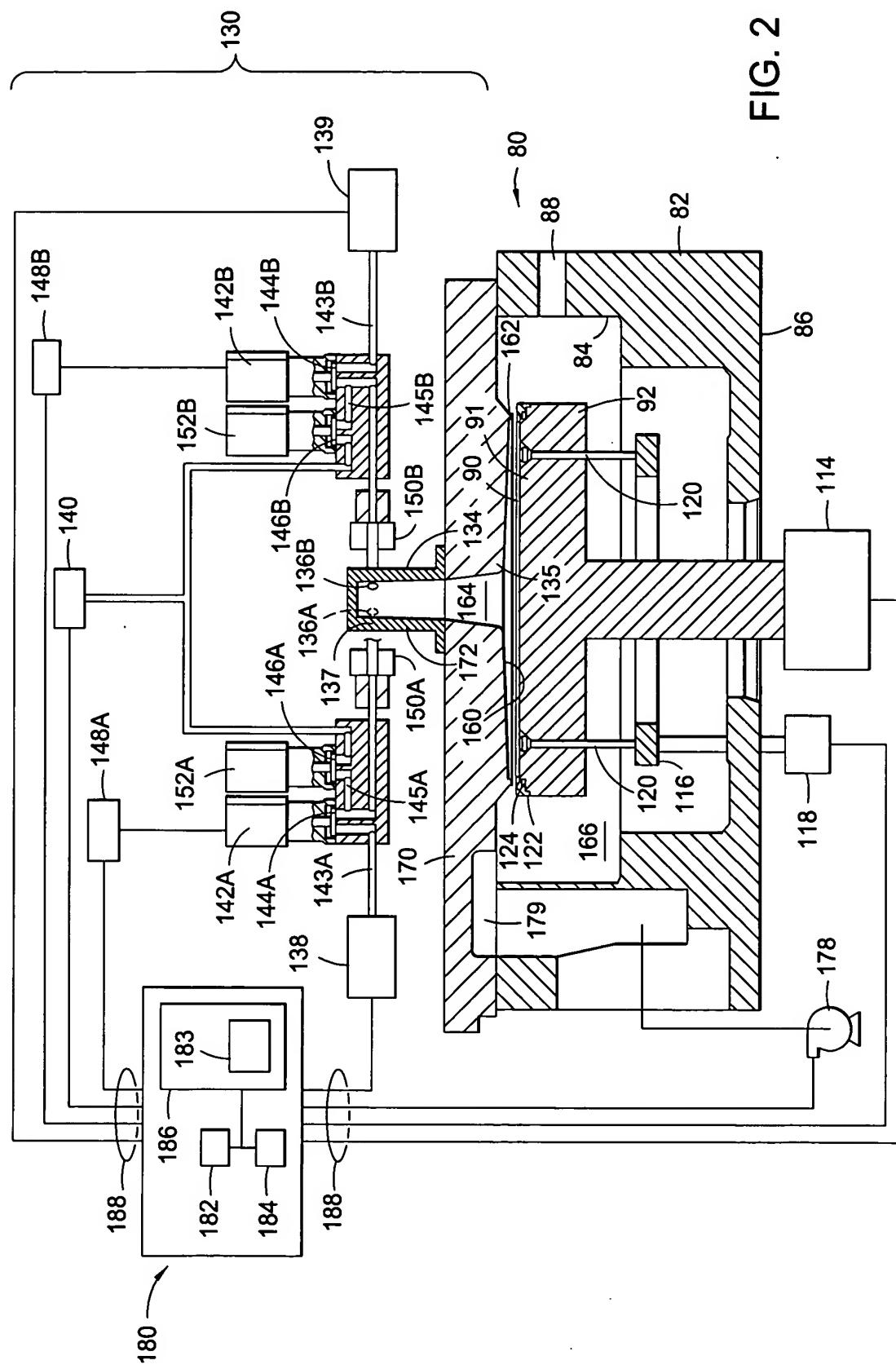


FIG. 2

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100

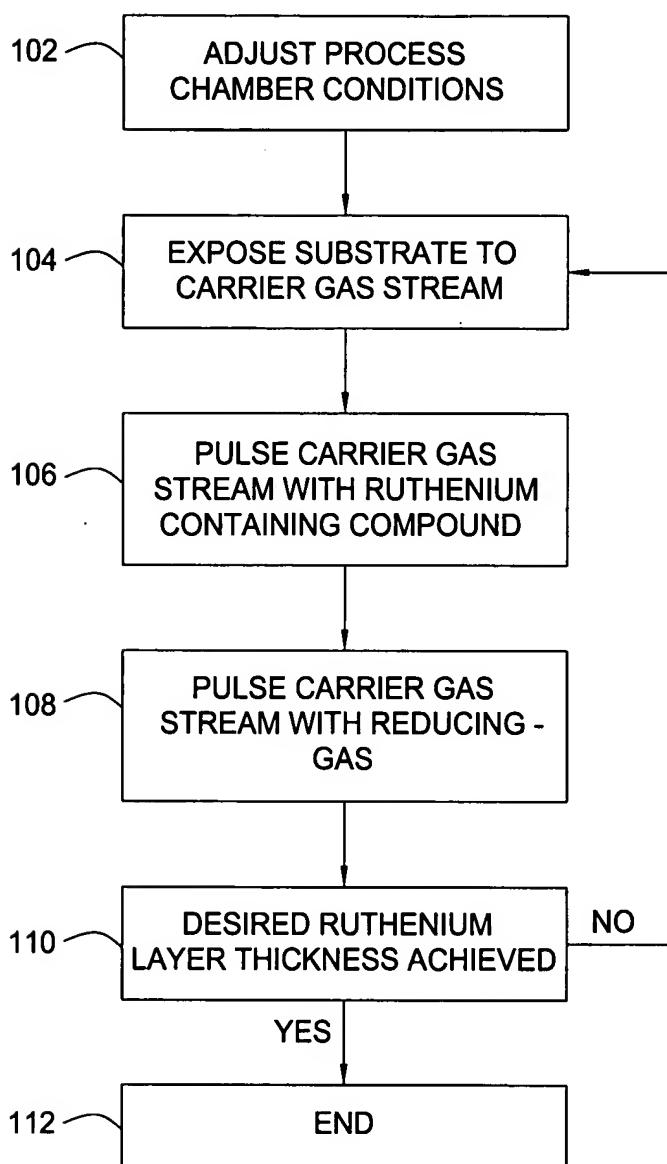


FIG. 3

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200

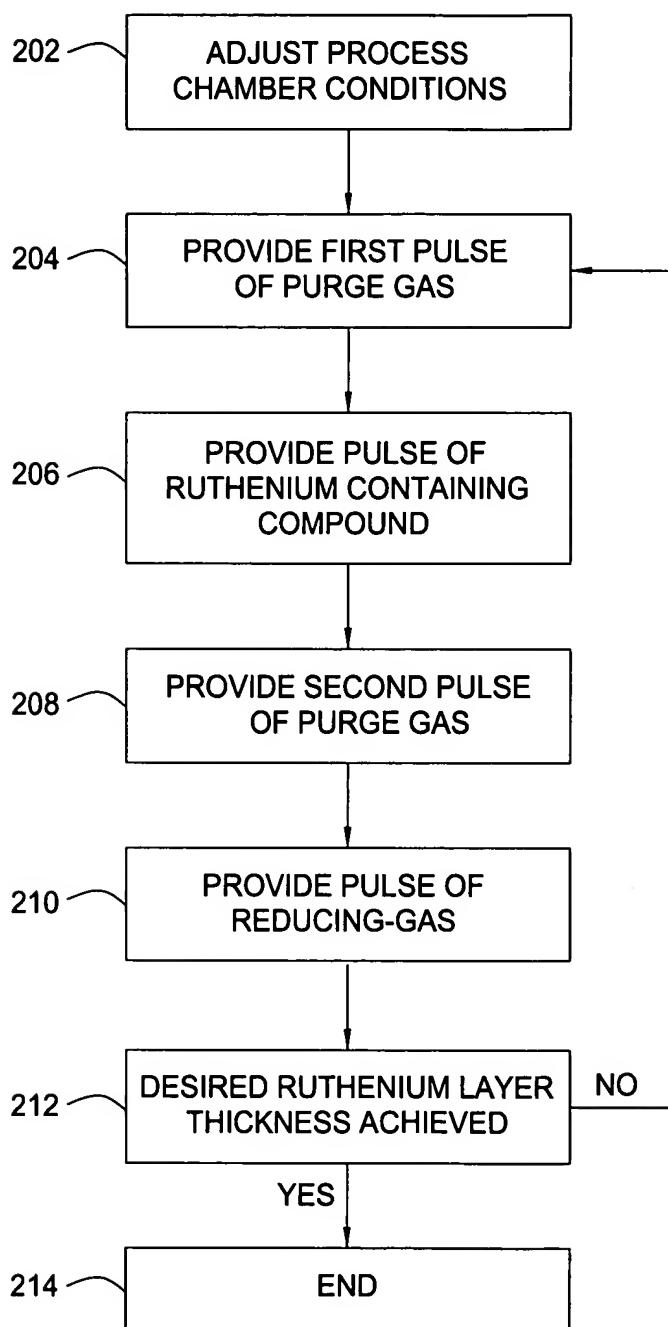


FIG. 4

ATTY DKT. NO.: AMAT/5975.P2/CPI/L/B/PJS
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: RUTHENIUM LAYER FORMATION FOR COPPER FILM
DEPOSITION
INVENTOR: GANGULI, ET AL.
EXPRESS MAIL No.: EV416701877US

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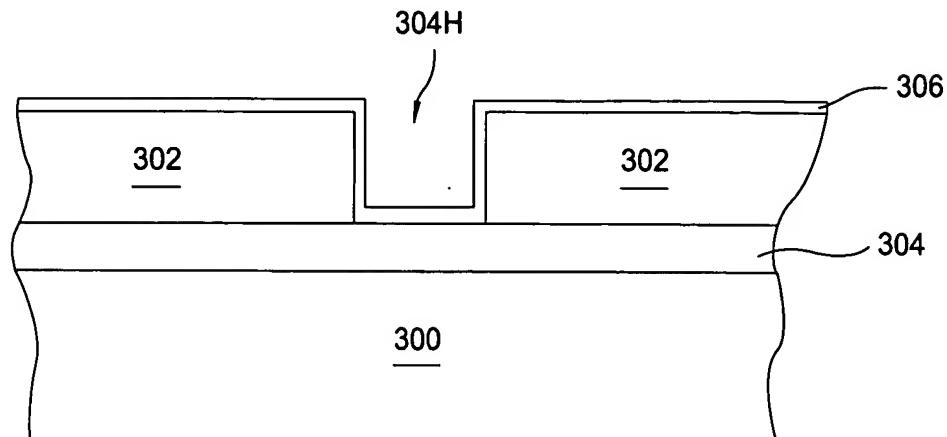


FIG. 5A

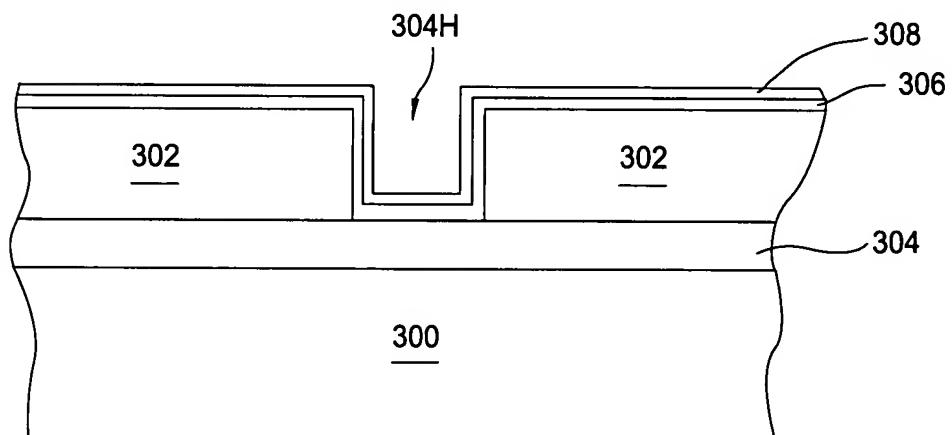


FIG. 5B

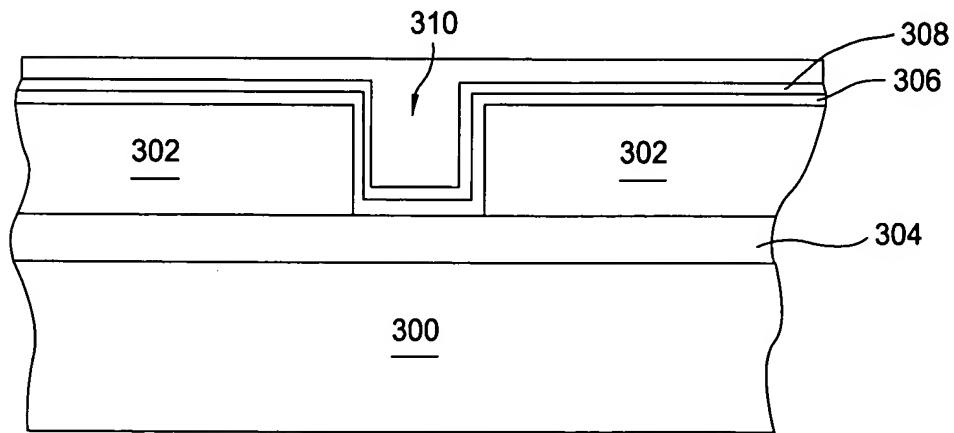


FIG. 5C